



Material Content Data Sheet



Sales Product Name		BGS 13MPA9 E6327		Issued		14. September 2018		
MA#		MA002172734						
Package		PG-ATSLP-9-3		Weight*		3.35 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.361	10.79	10.79	107875	107875
bumps	non noble metal	copper	7440-50-8	0.027	0.81	0.81	8142	8142
encapsulation	organic material	carbon black	1333-86-4	0.011	0.32		3227	
	plastics	epoxy resin	-	0.313	9.36		93597	
leadfinish	inorganic material	silicondioxide	60676-86-0	1.836	54.88	64.56	548675	645499
	noble metal	gold	7440-57-5	0.037	1.09		10914	
substrate	non noble metal	nickel	7440-02-0	0.042	1.24	2.33	12448	23362
	organic material	carbon black	1333-86-4	0.001	0.02		218	
solder	plastics	epoxy resin	-	0.028	0.85		8502	
	inorganic material	silicondioxide	60676-86-0	0.214	6.39		63949	
ubm	non noble metal	copper	7440-50-8	0.390	11.66	18.92	116559	189228
	noble metal	silver	7440-22-4	0.000	0.01		53	
solder resists	non noble metal	tin	7440-31-5	0.010	0.29	0.30	2900	2953
	non noble metal	tungsten	7440-33-7	0.000	0.00		6	
*deviation	non noble metal	titanium	7440-32-6	0.000	0.00		11	
	non noble metal	copper	7440-50-8	0.000	0.00	0.00	31	48
*deviation	inorganic material	silicondioxide	60676-86-0	0.016	0.49		4865	
	inorganic material	bariumsulfate	7727-43-7	0.016	0.49		4922	
*deviation	plastics	acrylic resin	-	0.044	1.31	2.29	13106	22893
						Sum in total:	100.00	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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